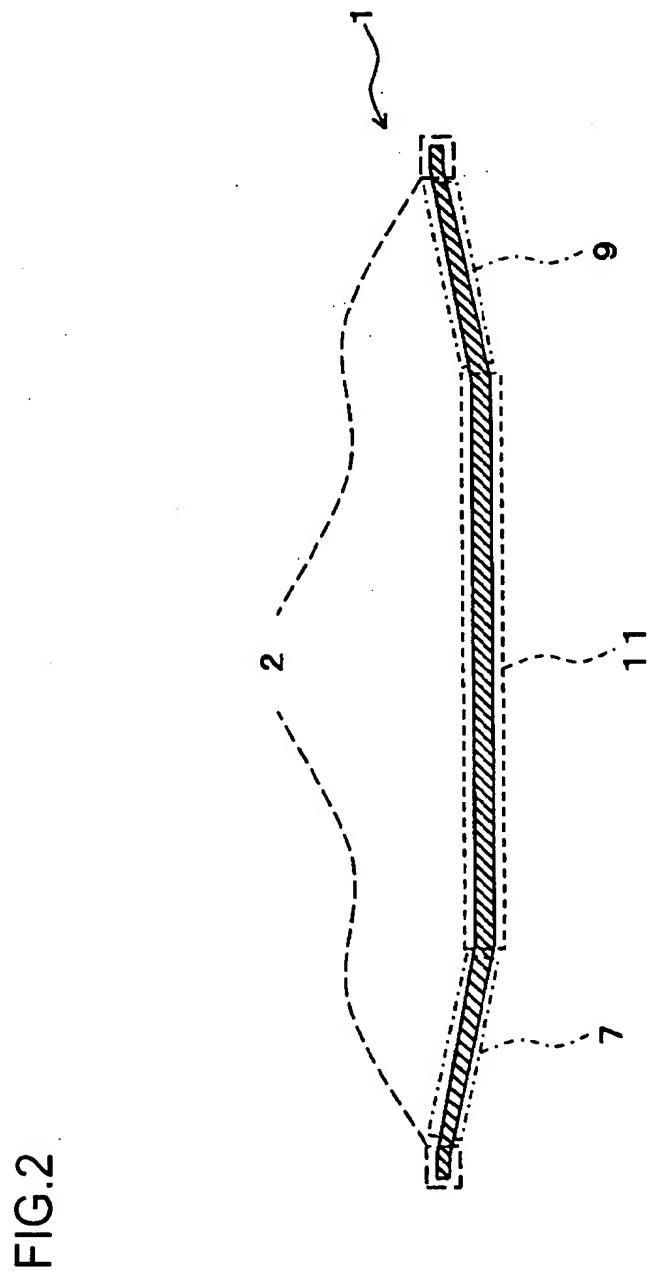


FIG.1

Title: LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE, METHOD FOR MANUFACTURING  
SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

Inventor: Yoshiro IWASA  
Atty. Ref.: 9319S-000666

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Title: LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE, METHOD FOR MANUFACTURING  
SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

Inventor: Yoshiro IWASA  
Atty. Ref.: 9319S-000666

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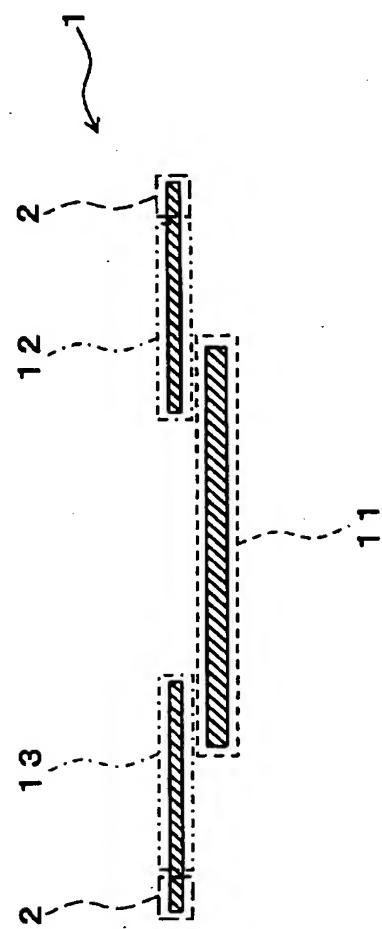


FIG.3

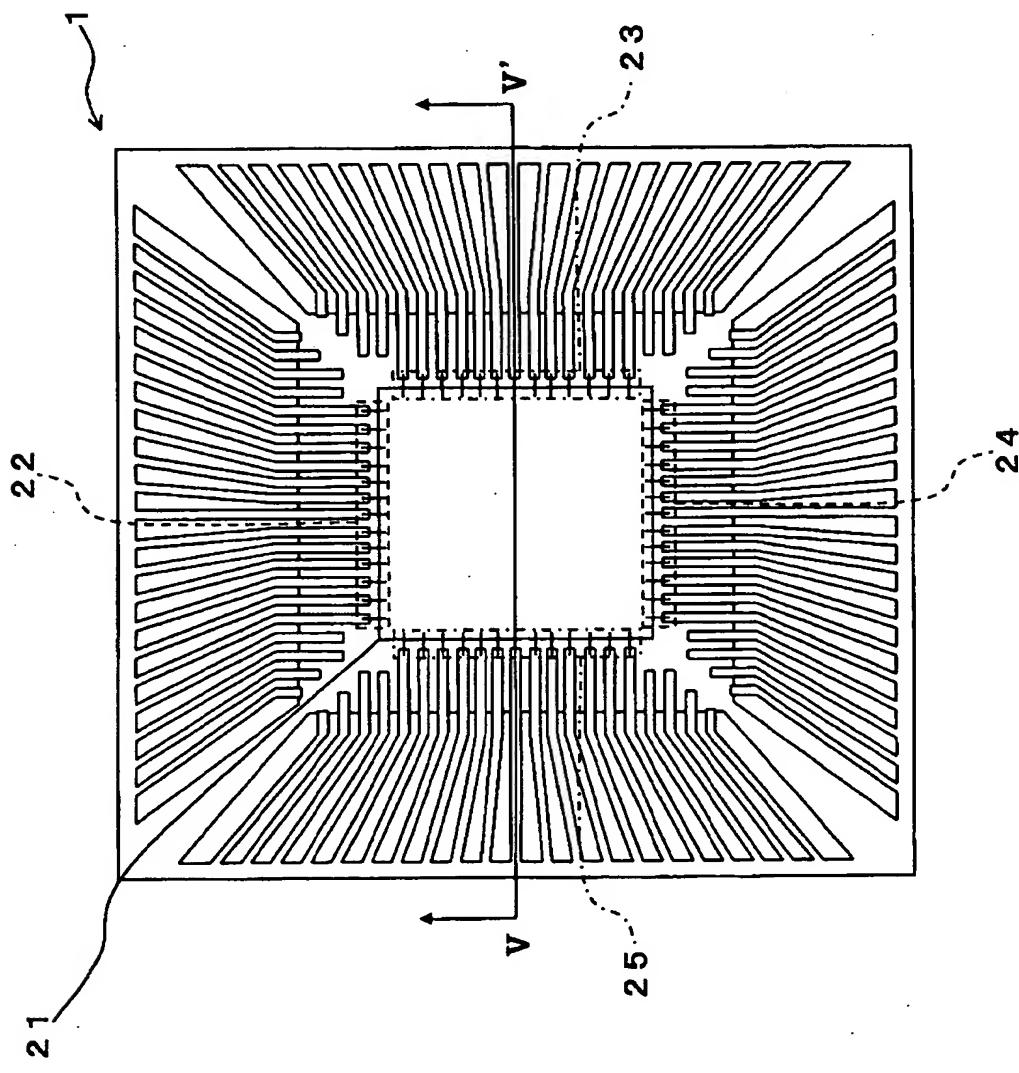


FIG.4

Title: LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE, METHOD FOR MANUFACTURING  
SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

Inventor: Yoshiro IWASA  
Atty. Ref.: 9319S-000666

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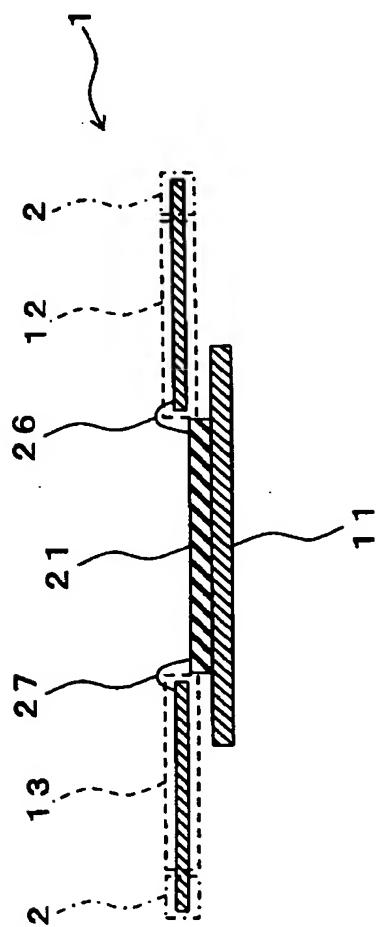


FIG.5

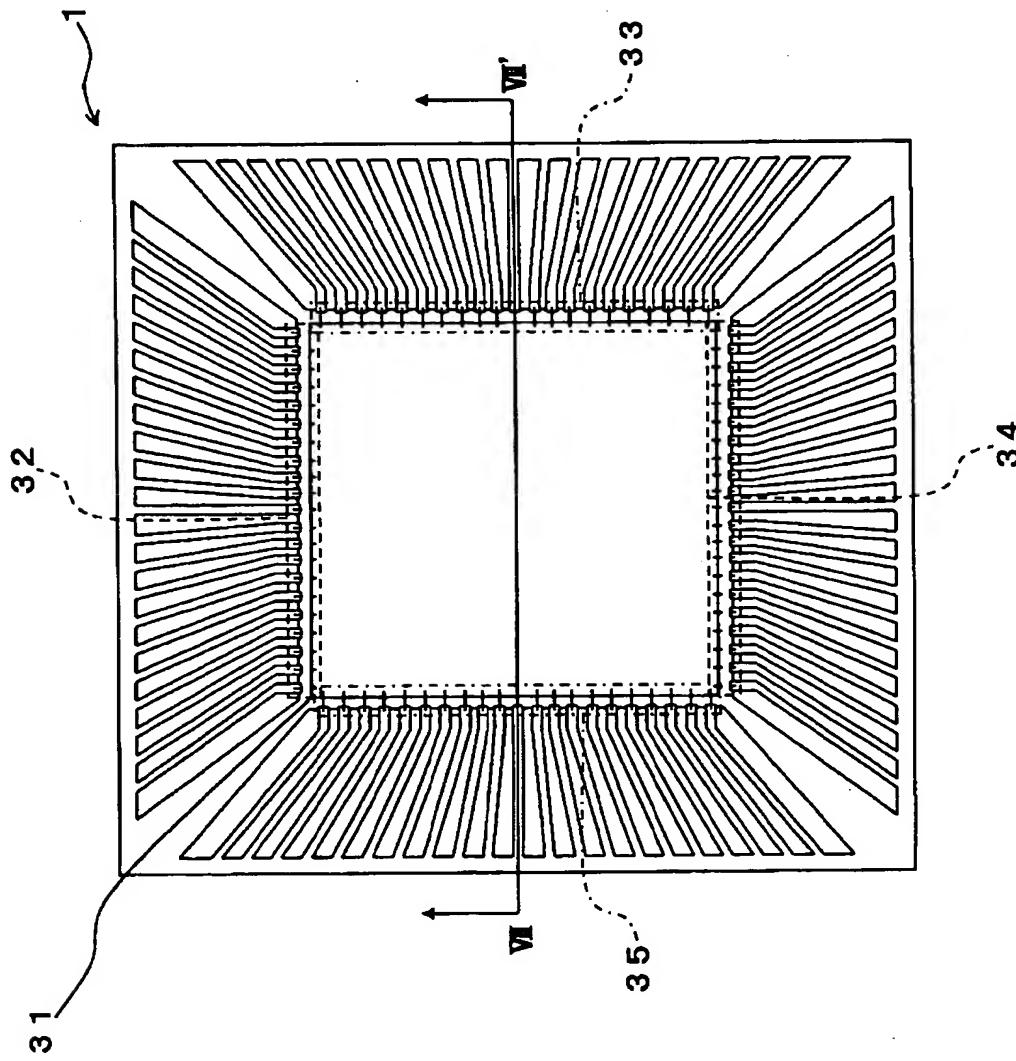


FIG.6

Title: LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE, METHOD FOR MANUFACTURING  
SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

Inventor: Yoshiro IWASA  
Atty. Ref.: 9319S-000666

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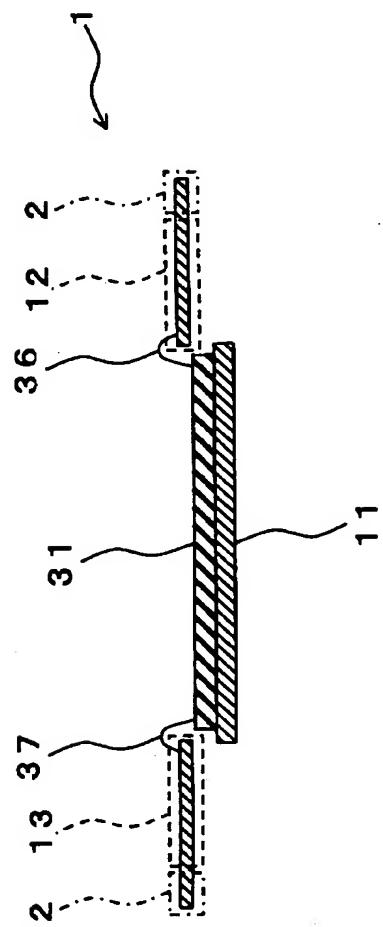


FIG.7

Title: LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE, METHOD FOR MANUFACTURING  
SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

Inventor: Yoshiro IWASA  
Atty. Ref.: 9319S-000666

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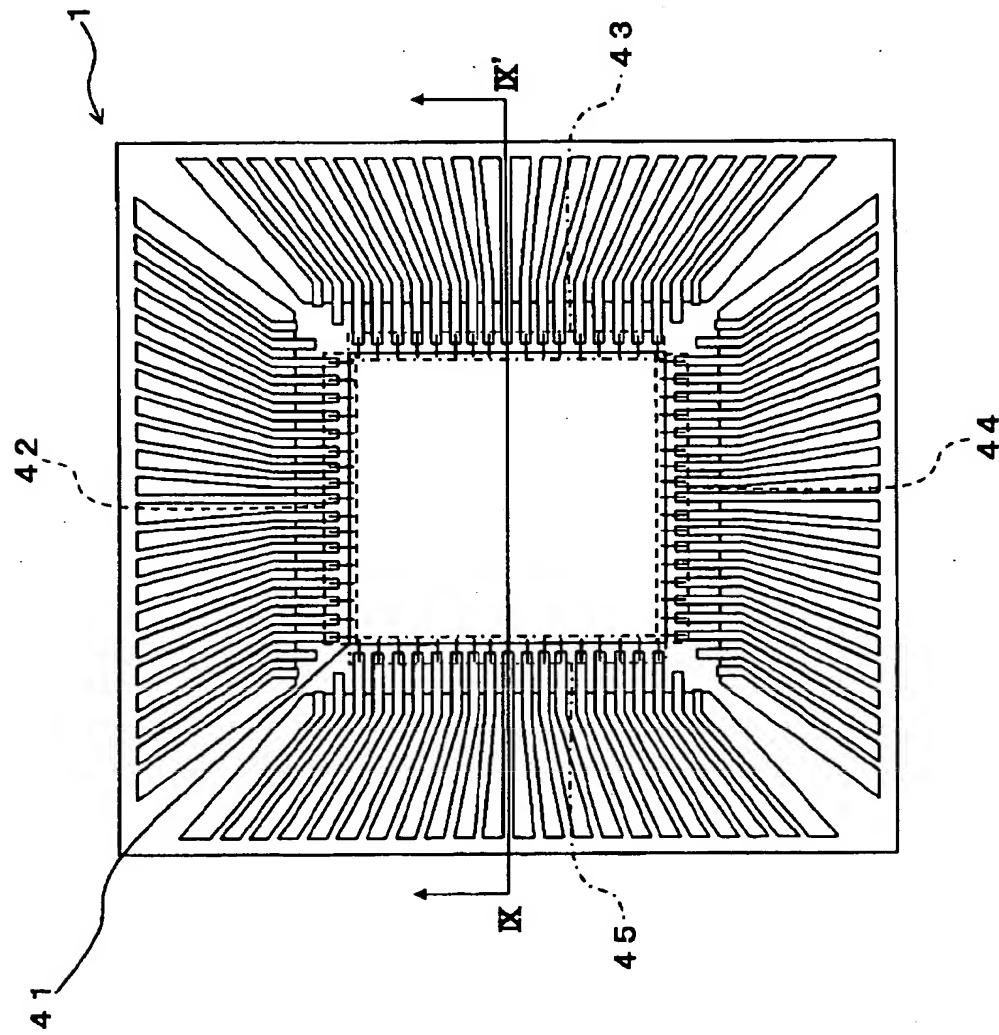


FIG.8

Title: LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE, METHOD FOR MANUFACTURING  
SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

Inventor: Yoshiro IWASA  
Atty. Ref.: 9319S-000666

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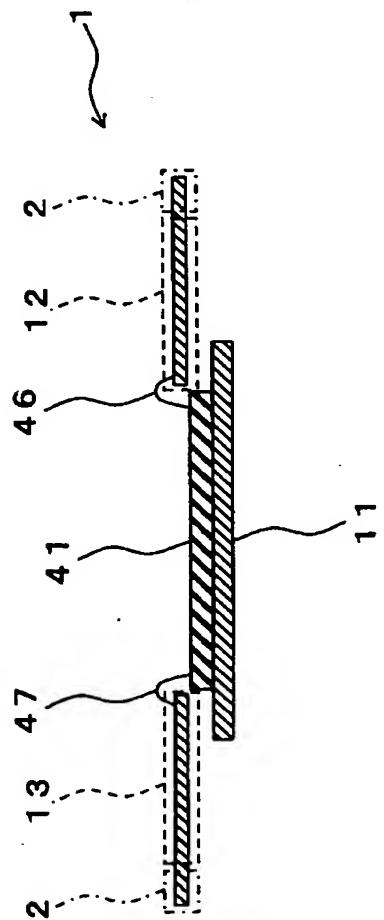
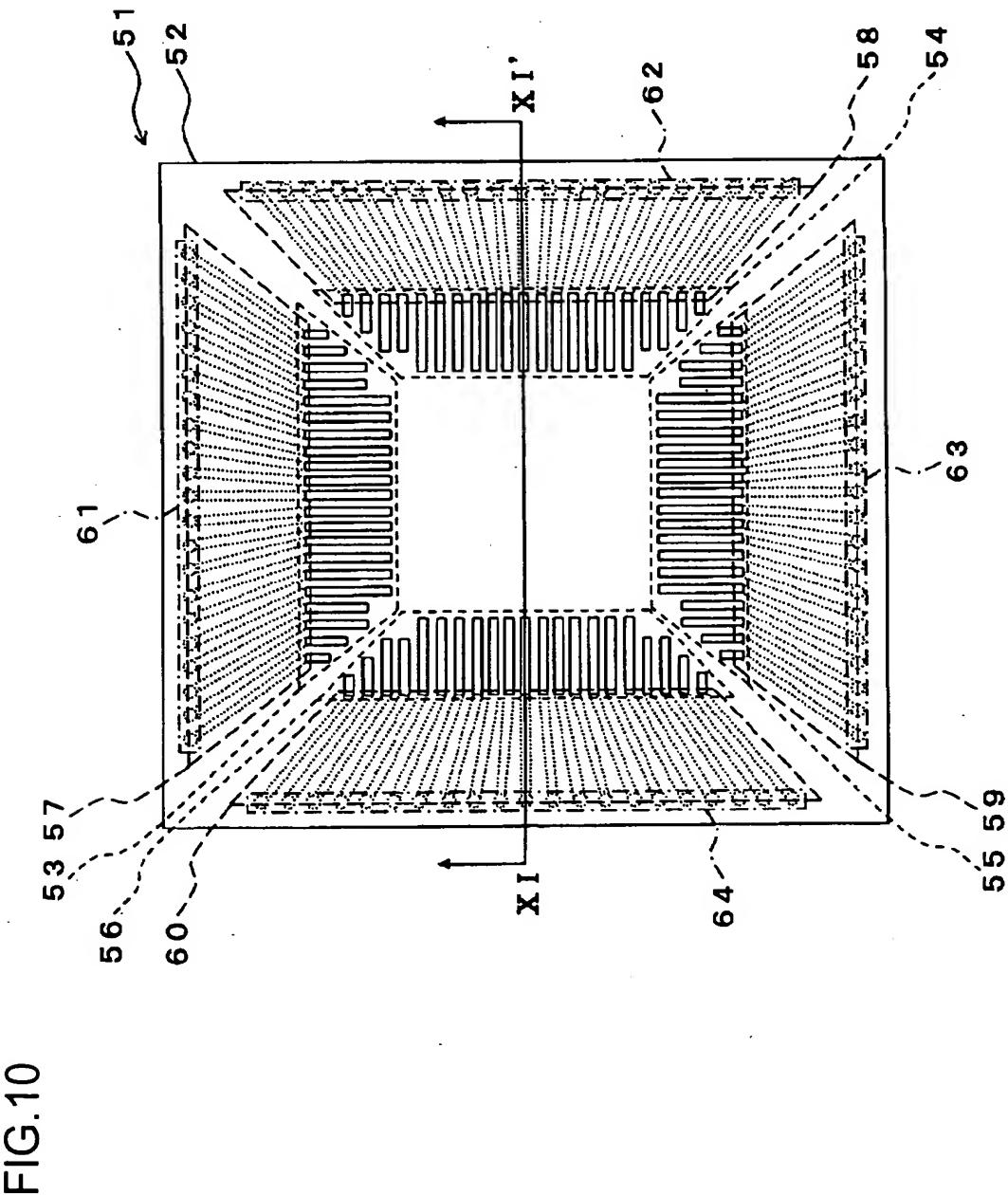


FIG.9



Title: LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE, METHOD FOR MANUFACTURING  
SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

Inventor: Yoshiro IWASA  
Atty. Ref.: 9319S-000666

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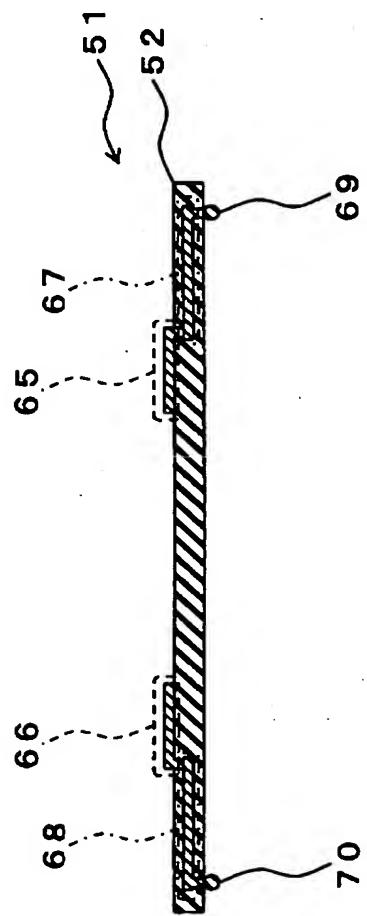


FIG.11

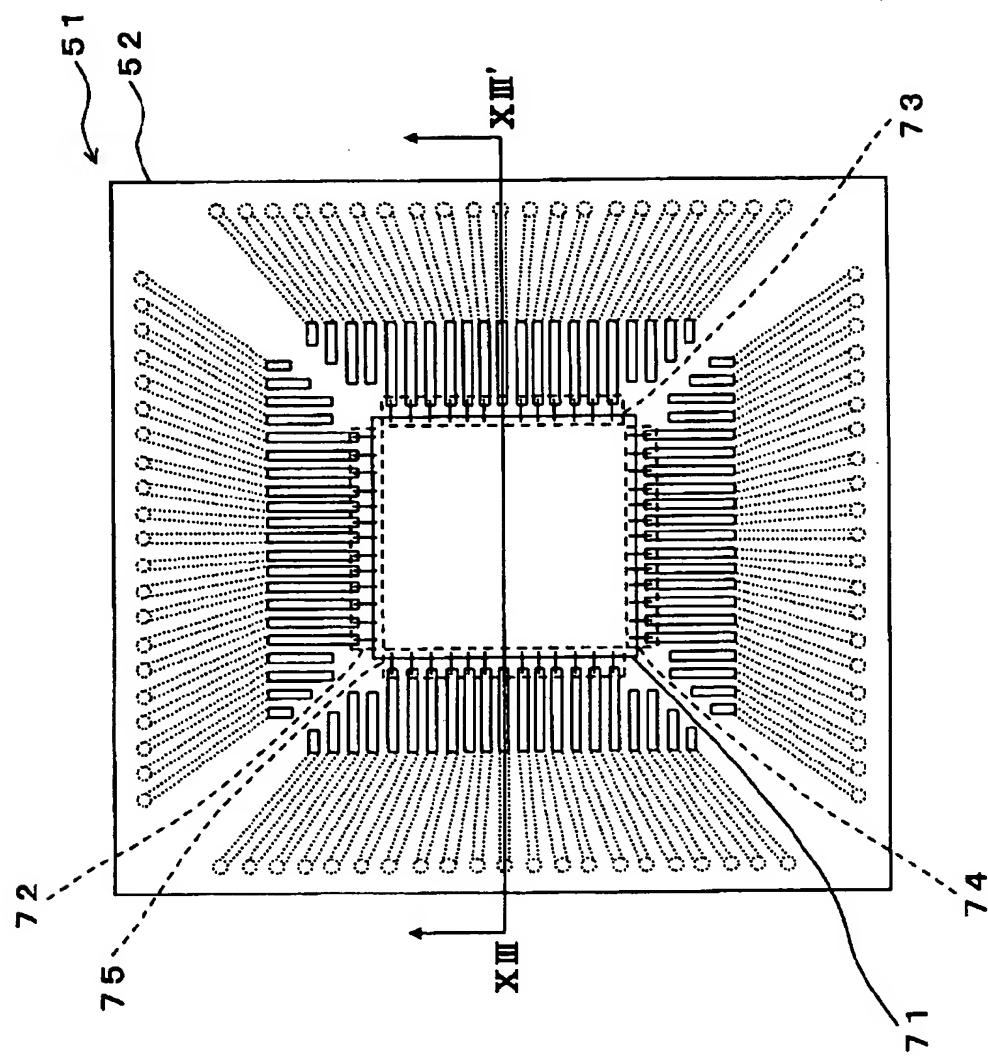


FIG. 12

Title: LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE, METHOD FOR MANUFACTURING  
SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

Inventor: Yoshiro IWASA  
Atty. Ref.: 9319S-000666

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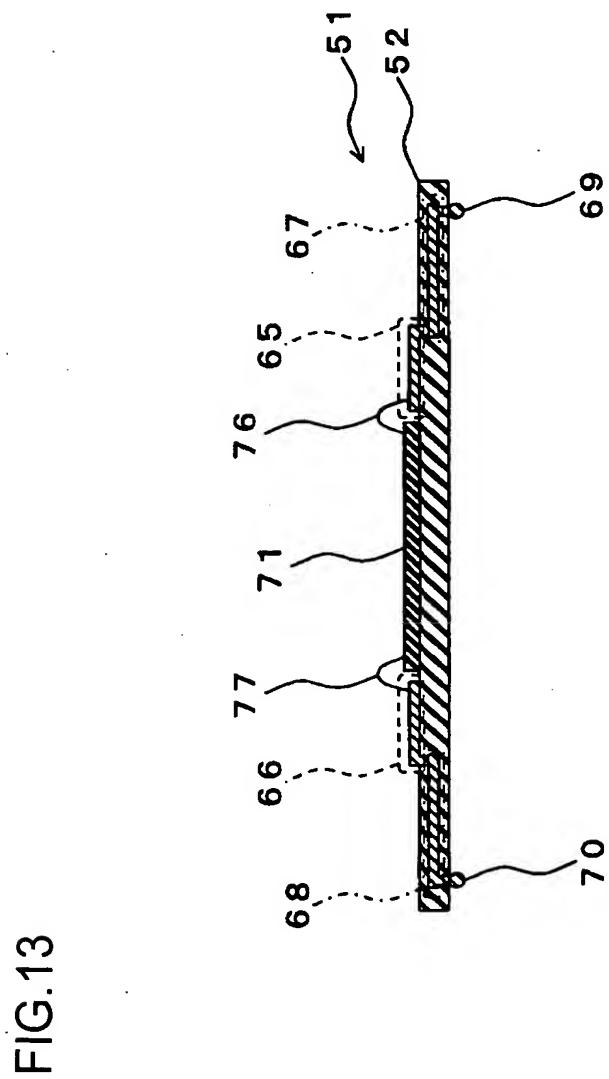


FIG.13

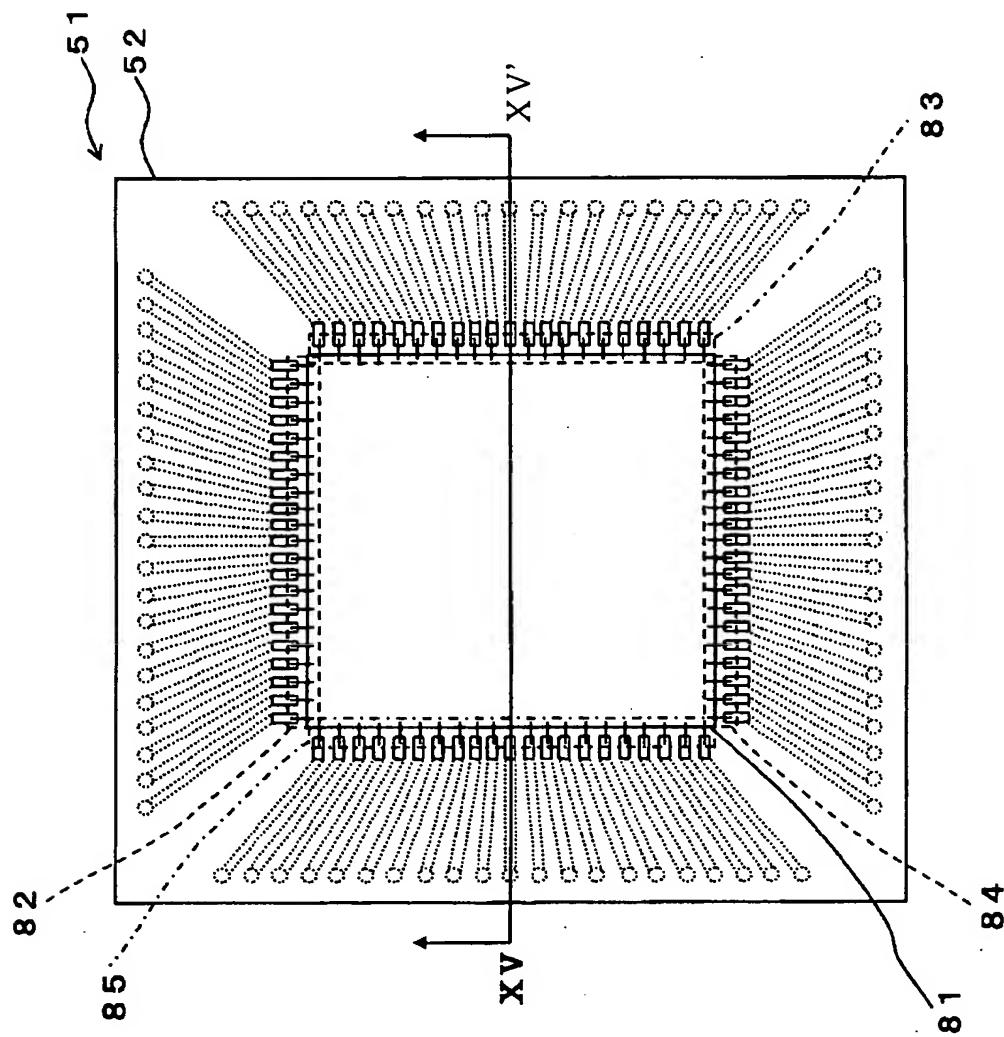


FIG.14

Title: LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE, METHOD FOR MANUFACTURING  
SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

Inventor: Yoshiro IWASA  
Atty. Ref.: 9319S-000666

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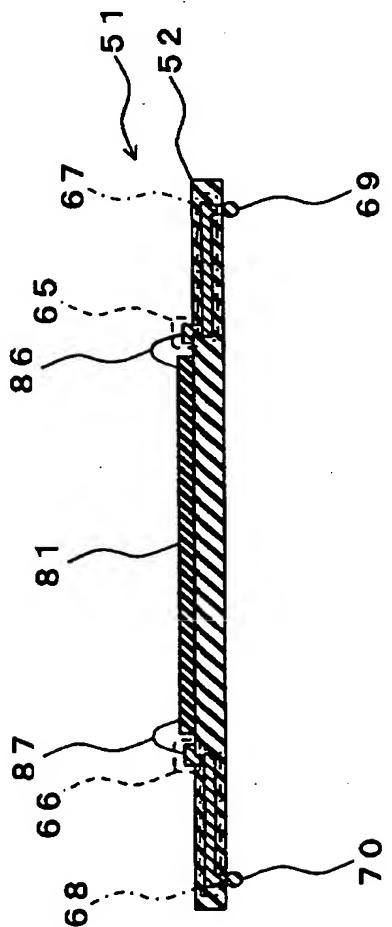


FIG.15

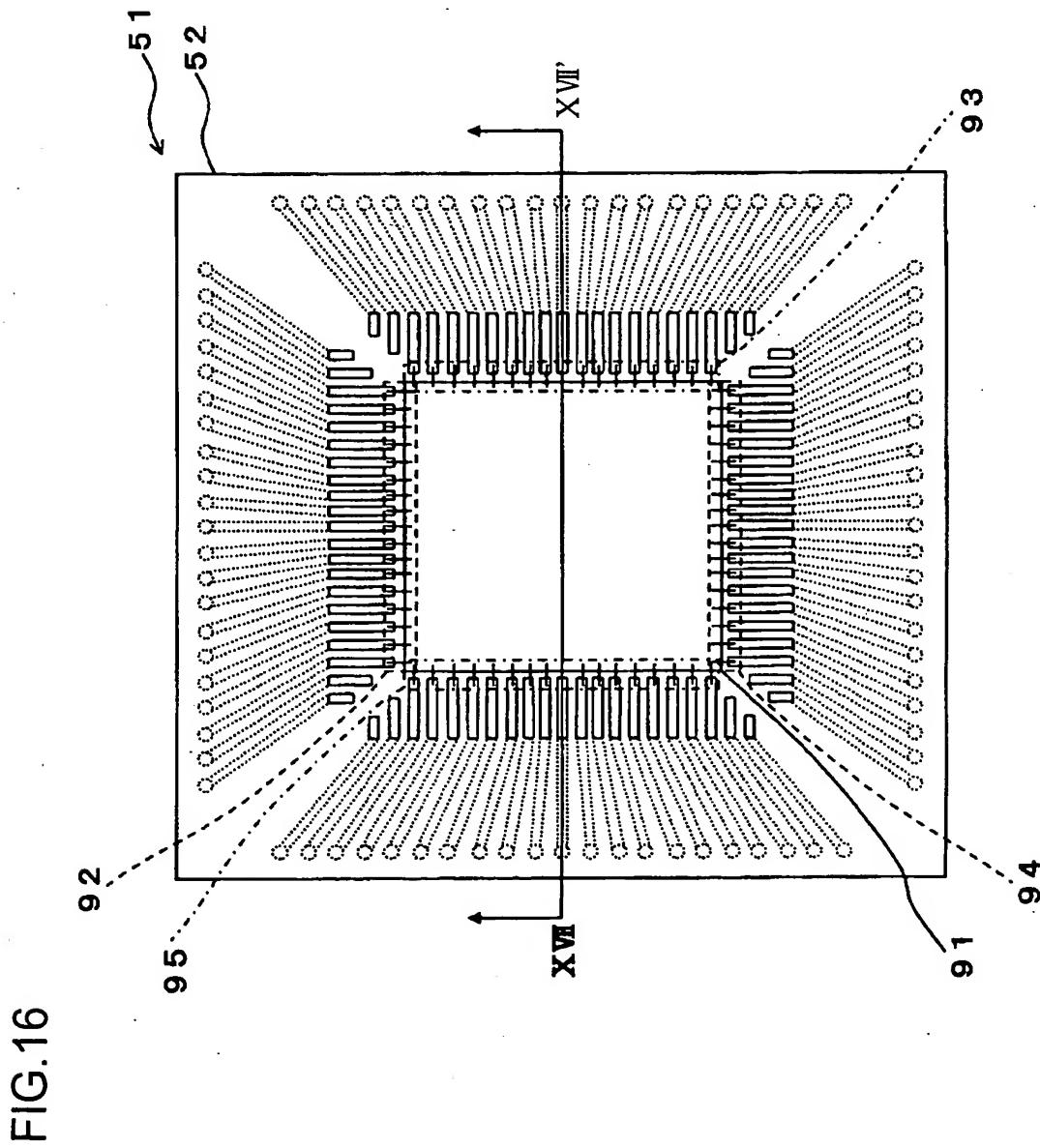


FIG.16

Title: LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE, METHOD FOR MANUFACTURING  
SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

Inventor: Yoshiro IWASA  
Atty. Ref.: 9319S-000666

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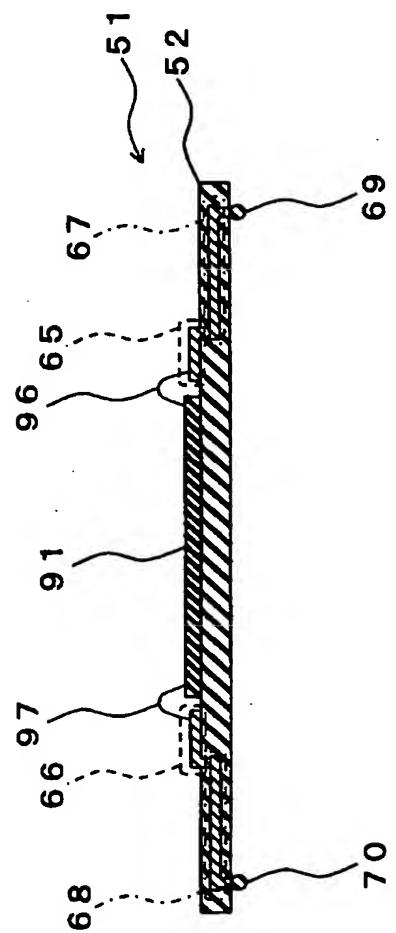


FIG.17

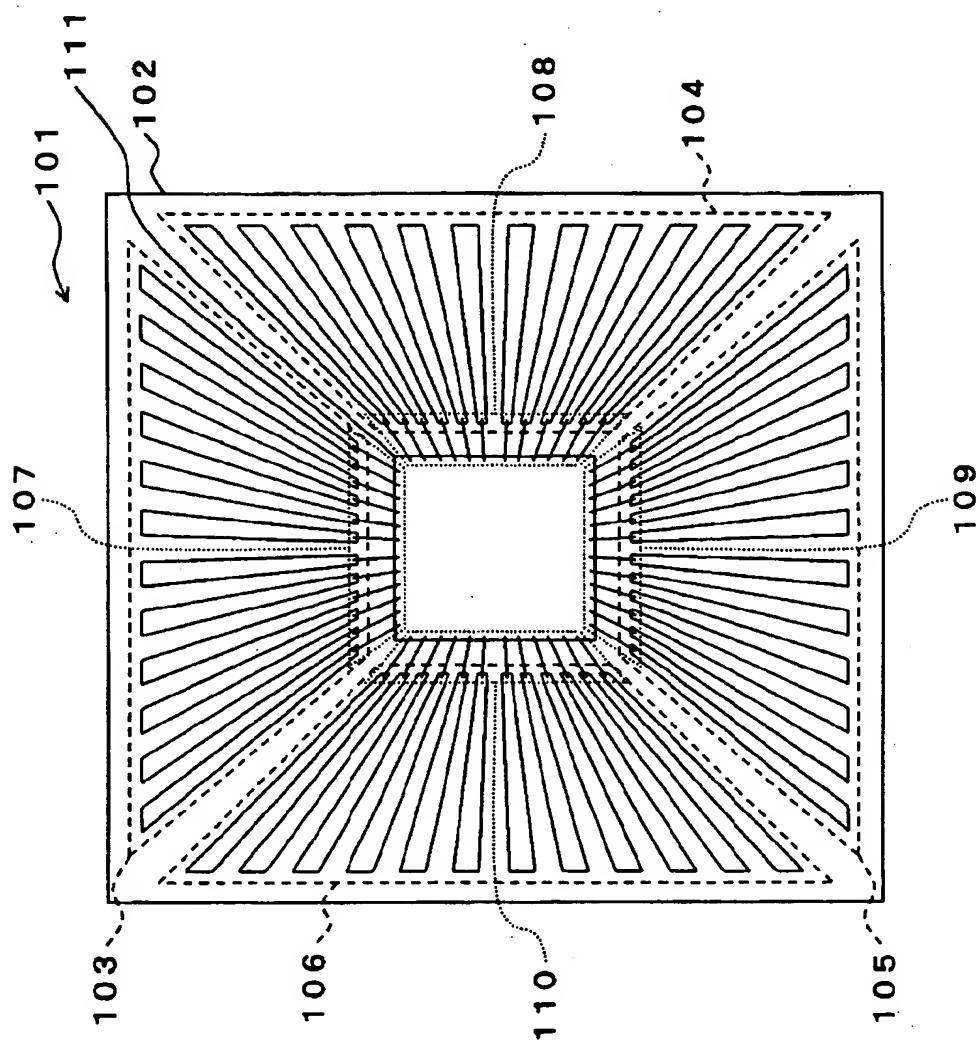


FIG.18